

**/ Descriptions**

Silicon NPN transistor in a SOT-323 Plastic Package.

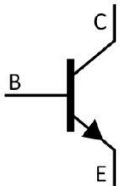
**/ Features**

Collectoe to emitter saturation voltage  $V_{ce(sat)}=0.3V_{max}$ Excellent lineality of DC forward current gain,Supper mini package for easy mounting.

**/ Applications**

For hybrid IC,small type machine low frequency voltage amplify application.

**/ Equivalent Circuit**



**/ Pinning**



PIN1 Emitter      PIN 2 Base      PIN 3 Collector

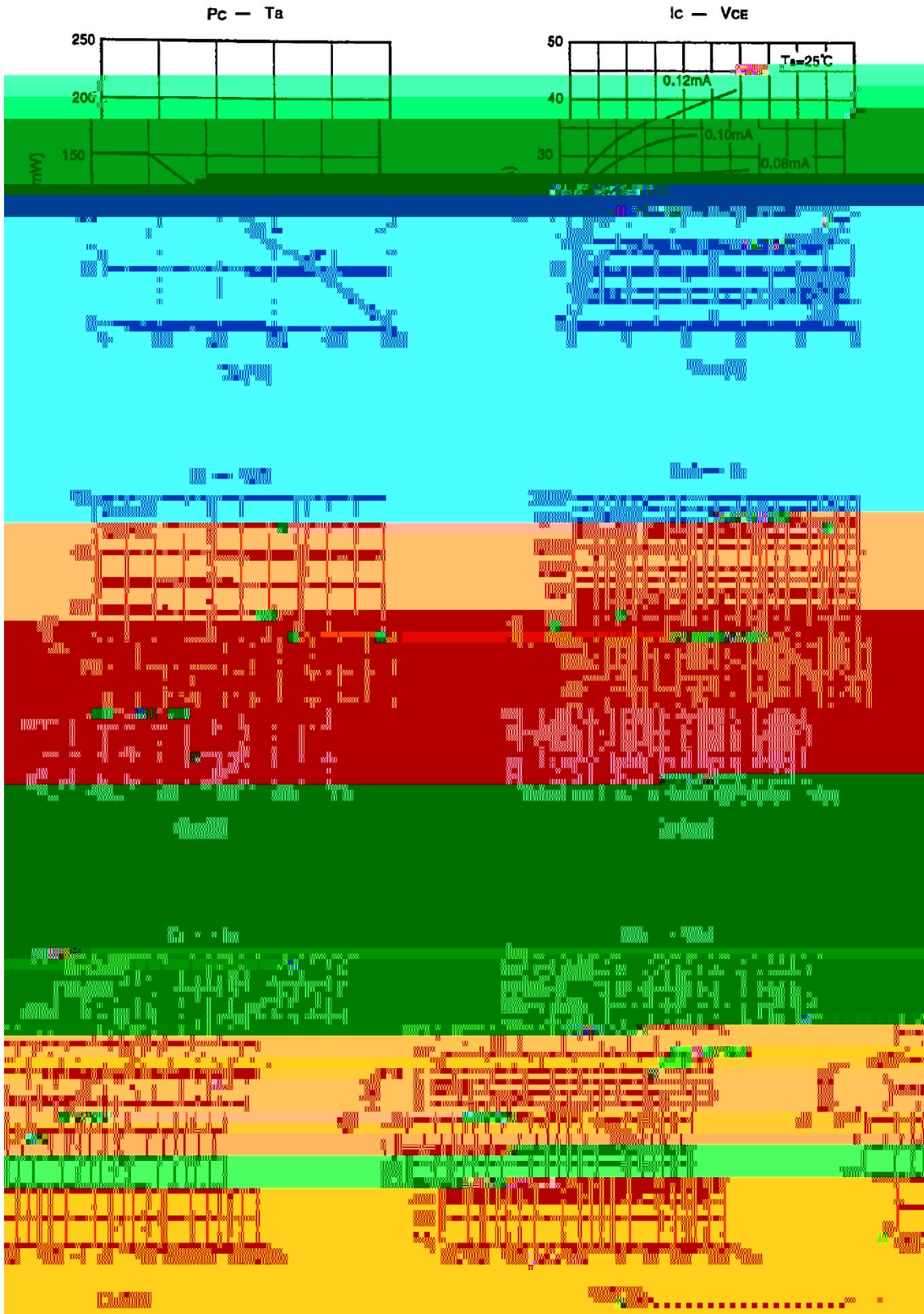
**/ Marking**

$h_{FE}$ Classifications Symbol	Q	R	S	T
$h_{FE}$ Range	120 270	180 390	270 560	390 820
Marking	HQH	HRH	HHS	HHT

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	50	V
Collector to Emitter Voltage	$V_{CEO}$	50	V
Emitter to Base Voltage	$V_{EBO}$	6	V
Collector Current - Continuous	$I_C$	2SC4155	0.1
		2SC4155A	0.2
Collector Power Dissipation	$P_C$	150	mW
Junction Temperature	$T_j$	125	°C
Storage Temperature Range	$T_{stg}$	-55 150	°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=0.1mA$ $R_{BE}=\infty$	50			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=50V$ $I_E=0$			0.5	$\mu A$
					0.1	
Emitter Base Cut-Off Current	$I_{EBO}$	$V_{EB}=4V$ $I_C=0$			0.1	$\mu A =0$

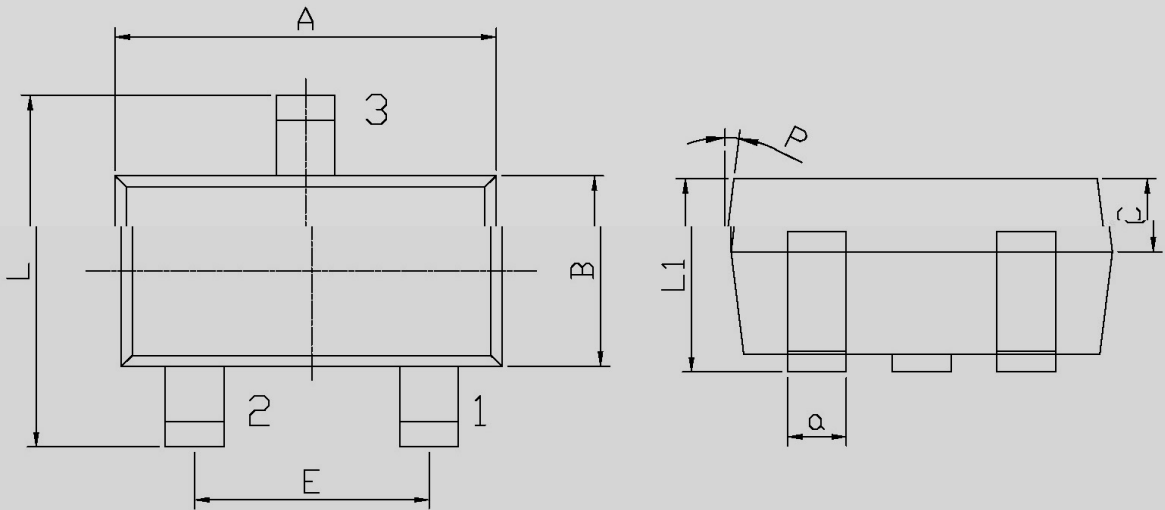
/ Electrical Characteristic Curve



/ Package Dimensions

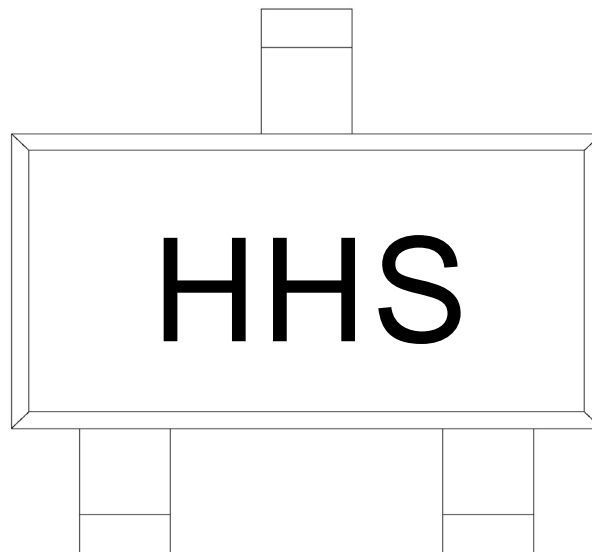
SOT-323

单位: mm



Symbol	Dimensions in Millimeters		Symbol	Dimensions in Millimeters	
	Min	Max		Min	Max
A	1.95	2.35	C	0.30	0.50
L	2.00	2.2	L1	0.85	1.15
E	1.20	1.40	a	0.20	0.40
R <sub>1</sub>	1.15	1.35	P	7°	

/ Marking Instructions



H

H

S             $h_{FE}$

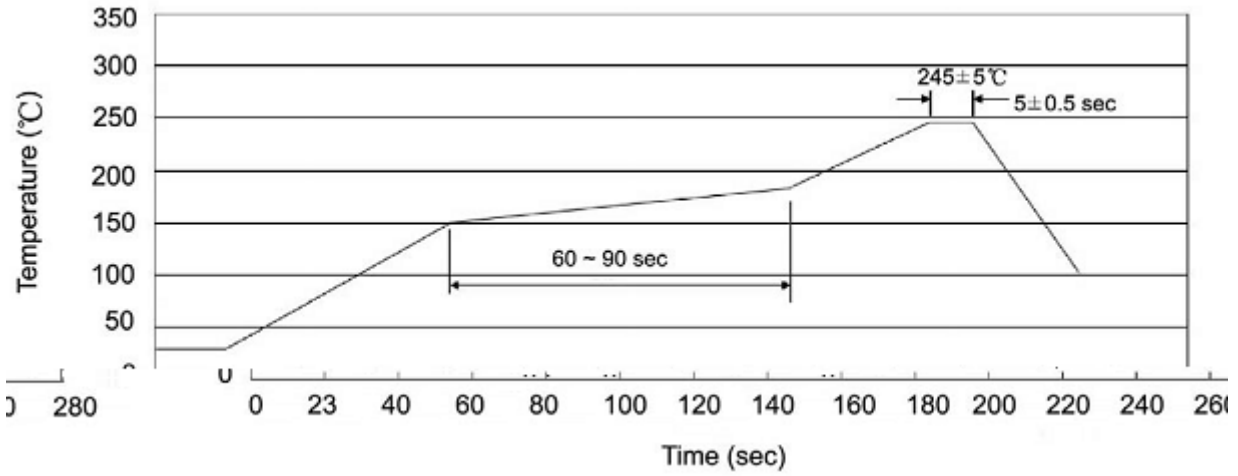
Note:

H:            Company Code.

H:            Product Type.

S:             $h_{FE}$  Classifications Symbol

( ) / K\d g\iXk i\`Gif]`Δ`]fi`@`I\`fn`Jfd\`i`e^`ZGY\$`i\`z



Note:

- |   |     |     |    |          |   |
|---|-----|-----|----|----------|---|
| 1 | 25  | 150 | 60 | 90sec;   | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 245 | 5   | 5  | 0.5sec;  | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 |     |     | 2  | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

260 5                      10 1 sec.                      Temp.:260±5°C                      Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	只卷盘	卷盘盒	只盒	盒箱	只箱	盒	箱	

/ Notices